LEI 1800CH-14mm

Contactless Sheet Resistance/Resistivity Measurement

Model 1800CH-14mm OEM - Ideally large samples, 300 mm wafer maximum

Characterization of

* **All compound semiconductor materials**
  - epi, annealed ion-implants on semi insulating and some doped substrates
* **Silicon wafers**
  - bulk Si, epi, annealed ion-implants, and POCl3 doping uniformity on high resistivity substrates
* **Thin film metallization**
  - Contact factory for details

Operating Characteristics

* Precise voltage regulation for tight linearity and consistently repeatable results

Sample Handling and Sensing

* Automatic drift compensation
* Software-selectable resistivity ranges

Benefits

* Lower operation cost
* Perform non-destructive measurements
* Minimal non-contact calibration
* Measurement heads are permanent
* Measurement range selected easily
* No product wafer contamination
* Ideal for mounted inline in production line

Measurement Capabilities

* Normal coil gap (≥ 0.35”/8.89 mm)
* Wafer sizes: 3” (75 mm) to 12” (300 mm)
* Manual loading

Sensor Transducer Size

* 14 mm diameter for all ranges

Accessories and Options

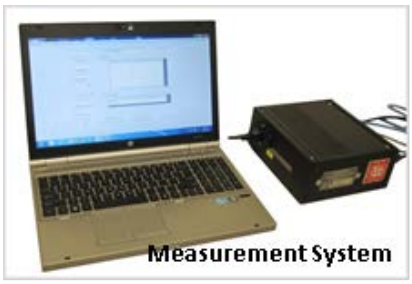
* Options that allow for turnkey standalone operations (R&D)

Nondestructive Measurement of Semiconductor Wafers

Specifications

Range *	Sheet Res. (ohm/sq.)
Hi	16 - 3000
Lo	0.16 - 16
XLo	0.035 - 1.6

*each range sold separately



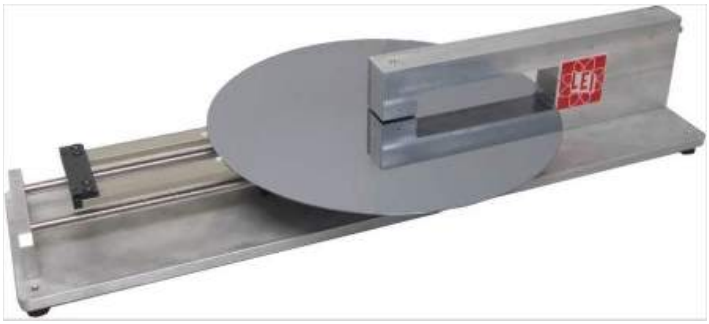


Figure 1: Model 1800CH-14MM

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